

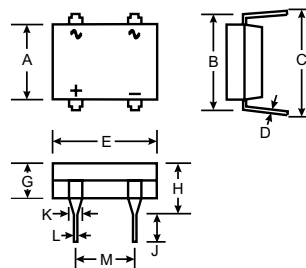
### DB101 ---DB107

#### FEATURES

- UL Recognized Component
- Ideal for Printed Circuit Board
- Glass Passivated Chip Junctions, Surge Overload Rating of 50A Peak
- Simple, Compact Structure for Trouble-free Performance
- Plastic Package - UL Flammability Classification 94V-0

#### Mechanical Data

- Terminals: Tin Plated Leads Solderable per MIL-STD-202, Method 208
- Case: Transfer Molded Epoxy
- Mounting Position: Any
- Polarity: Polarity Symbols Marked on Body
- Approx. Weight: 1.0 grams



DB-1		
Dim	Min	Max
A	6.10	6.60
B	7.11	8.13
C	8.13	9.40
D	0.20	0.38
E	-	9.40
G	-	3.30
H	-	5.51
J	2.80	3.68
K	1.02	1.40
L	0.51 Typical	
M	5.15 Typical	
All Dimensions in mm		

#### Maximum Ratings and Electrical Characteristics (Ta=25 °C unless otherwise noted)

Characteristic	Symbol	DB 101	DB 102	DB 103	DB 104	DB 105	DB 106	DB 107	Unit
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS Input Voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Rectified Output Current @ $T_A = 40^{\circ}C$	$I_{(AV)}$	1.0							A
Peak Forward Surge Current Single Half Sine-wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	50							A
Maximum Instantaneous Forward Voltage drop per Element at $I_F = 1.0A$	$V_F$	1.1							V
Maximum Reverse DC Current at Rated DC Blocking Voltage per Element	$I_R$	10 1.0							$\mu A$ mA
Typical Thermal Resistance (Note 1)	$R_{\theta JA}$	40							K/W
Storage and Operating Temperature Range	$T_J, T_{STG}$	-55 to +150							$^{\circ}C$

- Notes:
1. Thermal resistance from junction to ambient mounted on PC board with 13mm x 13mm copper pads.
  2. 60 Hz resistive or inductive load.
  3. For capacitive load, derate current by 20%.

**DB101---DB107 CHARACTERISTIC CURVES**

